



**THE DATASHEET OF  
MPC566MVR56**



**Product Brief**

MPC565PB/D  
Rev. 3, 2/2003

MPC565/MPC566  
Product Brief


This document provides an overview of the MPC565/MPC566 microcontrollers, including a block diagram showing the major modular components, sections that list the major features, and differences between the MPC565/MPC566 and the MPC555. The MPC565 and MPC566 devices are members of the Motorola MPC500 RISC Microcontroller family. The parts herein will be referred to only as MPC565 unless specific parts need to be referenced.

**Table 1. MPC565/MPC566 Features**

Device	Flash	Code Compression
MPC565	1 Mbyte	Code compression not supported
MPC566	1 Mbyte	Code compression supported

# 1 Introduction

The MPC565 device offers the following features:

- PowerPC™ core with a floating point unit (FPU) and a burst buffer controller (BBC)
- Unified system integration unit (USIU), a flexible memory controller, and improved interrupt controller
- 1 Mbyte of Flash memory (UC3F)
  - Typical endurance of 100,000 write/erase cycles @ 25°C
  - Typical data retention of 100 years @ 25°C
- 36 Kbytes of static RAM (two CALRAM modules)
  - 8 Kbytes of normal access or overlay access (sixteen 512-byte regions)
  - 4 Kbytes in CALRAM A, 4 Kbytes in CALRAM B
- Three time processor units (TPU3)
  - TPU3 A and TPU3 B are connected to DPTRAM AB (6 Kbytes)
  - TPU3 C is connected to DPTRAM C (4 Kbytes)
- A 22-timer channel modular I/O system (MIOS14)
  - Same as MIOS1 plus a real-time clock sub-module (MRTCSM), 4 counter sub-modules (MCSM), and 4 PWM sub-modules (MPWMSM)
- Three TouCAN modules (TouCAN\_A, TouCAN\_B, and TouCAN\_C)
- Two enhanced queued analog to digital converters (QADC64E A, QADC64E B) with analog multiplexers (AMUX) for 40 total analog channels. These modules are configured so each module can access all 40 of the analog inputs to the part.

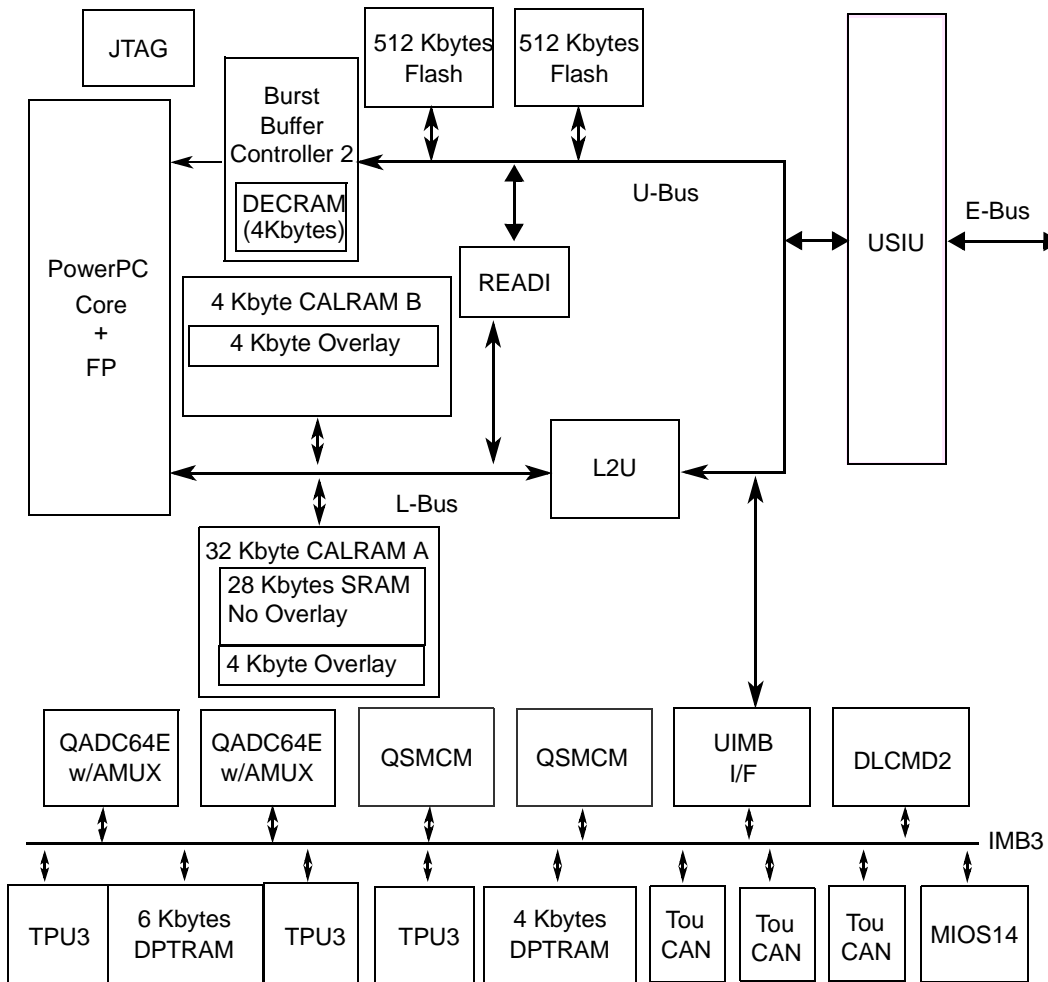
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**Block Diagram**

- Two queued serial multi-channel modules (QSMCM A, QSMCM B), each of which contains a queued serial peripheral interface (QSPI) and two serial controller interfaces (SCI/UART)
- -40°C – 125°C ambient temperature, -40°C – 85°C for suffix C devices, -55°C– 125°C for suffix A devices
- Debug features:
  - A J1850 (DLCMD2) communications module
  - A Nexus debug port (class 3) – IEEE-ISTO 5001-1999
  - JTAG and background debug mode (BDM)
- Packaging and Electrical

## 1.1 Block Diagram

Figure 1 is a block diagram of the MPC565.



**Figure 1. MPC565 Block Diagram**

## 1.2 Detailed Feature List

The MPC565 key features are explained in the following sections.

### 1.2.1 High Performance CPU System

- Fully static design
- Four major power saving modes
  - On, doze, sleep, deep-sleep and power-down

### 1.2.2 RISC MCU Central Processing Unit (RCPU)

- High-performance core
  - PowerPC single issue integer core
  - Precise exception model
  - Floating point
  - Code compression (MPC566 only)
    - Compression reduces usage of internal or external Flash memory
    - Compression optimized for automotive (non-cached) applications
    - New compression scheme decreases code size to 40% –50% of source

### 1.2.3 MPC500 System Interface (USIU)

- MPC500 system interface (USIU, BBC, L2U)
- Periodic interrupt timer, bus monitor, clocks, decremter and time base
- Clock synthesizer, power management, reset controller
- External bus tolerates 5-V inputs, provides 2.6-V outputs
- Enhanced interrupt controller supports a separate interrupt vector for up to eight external and 40 internal interrupts
- IEEE 1149.1 JTAG test access port
- Bus supports multiple master designs
- USIU supports dual-mapping of Flash to move part of internal Flash memory to external bus for development
- External bus, supporting non-wraparound burst for instruction fetches, with up to 8 instructions per memory cycle

### 1.2.4 Burst Buffer Controller (BBC) Module

- Exception vector table relocation features allow exception table to be relocated to following locations:
  - 0x0000 0000 - 0x0000 1FFF (normal MPC500 exception table location)
  - 0x0001 0000 - 0x0001 1FFF (0 + 64 Kbytes; second page of internal Flash)
  - Second internal Flash module
  - Internal SRAM
  - 0x0FFF\_0100 (external memory space; normal MPC500 exception table location)

## 1.2.5 Flexible Memory Protection Unit

- Flexible memory protection units in BBC (IMPU) and L2U (DMPU)
- Default attributes available in one global entry
- Attribute support for speculative accesses

## 1.2.6 Memory Controller

- Flexible chip selects via memory controller
- 24-bit address and 32-bit data buses
- 4- to 16-Mbyte (data) or 4-Gbyte (instruction) region size support
- Four-beat transfer bursts, two-clock minimum bus transactions
- Use with SRAM, EPROM, Flash and other peripherals
- Byte selects or write enables
- 32-bit address decodes with bit masks
- Four instruction regions
- Four data regions

## 1.2.7 1 Mbyte of CDR3 Flash EEPROM Memory (UC3F)

- 1 Mbyte Flash
  - Two UC3F modules, 512 Kbytes each
- Page mode read
- Block (64-Kbyte) erasable
- External 4.75- to 5.25-V VPP program and erase power supply
- Typical endurance of 100,000 write/erase cycles @ 25°C
- Typical data retention of 100 years @ 25°C

## 1.2.8 36-Kbyte Static RAM (CALRAM)

- 36-Kbyte static calibration RAM
  - Composed of 4-Kbyte and 32-Kbyte CALRAM modules
- Fast access: one clock
- Keep-alive power
- Soft defect detection (SDD)
- 4 Kbyte calibration (overlay) RAM per module (8 Kbytes total)
- Eight 512-byte overlay regions per module (16 regions total)

## 1.2.9 General Purpose I/O Support (GPIO)

- General-purpose I/O support
- Address (24) and data (32) pins can be used as GPIO in single-chip mode
- 16 GPIO in MIOS14
- Many peripheral pins can be used as GPIO when not used as primary functions
- 5-V outputs with slew rate control

## 1.2.10 Debug Features

- Extensive system debug support
- On-chip watchpoints and breakpoints
- Program flow tracking
- Background debug mode (BDM)

### 1.2.10.1 Nexus Debug Port (Class 3)

- Nexus/IEEE – ISTO 5001-1999 debug port (Class 3)
- Nine- or 16-pin interface

### 1.2.10.2 Message Data Link Controller (DLCMD2) Module

- Two pins muxed with QSMCMB pins. Muxing controlled by QSMCMB PCS3 pin assignment register
- SAE J1850 Class B data communications network interface compatible and ISO compatible for low-speed (<125 Kbps) serial data communications in automotive applications
- 10.4 Kbps variable pulse width (VPW) bit format
- Digital noise filter, collision detection
- Hardware cyclical redundancy check (CRC) generation and checking
- Block mode receive and transmit supported
- 4x receive mode supported (41.6 Kbps)
- Digital loopback mode
- In-frame response (IFR) types 0, 1, 2, and 3 supported
- Dedicated register for symbol timing adjustments
- Inter-module bus 3 (IMB3) slave interface
- Power-saving IMB3 stop mode with automatic wakeup on network activity
- Power-saving IMB3 CLOCKDIS mode
- Debug mode available through IMB3 FREEZE signal or user controllable SOFT\_FRZ bit
- Polling and IMB3 interrupt generation with vector lookup available

## 1.2.11 Integrated I/O System

- True 5-V I/O

### 1.2.11.1 Time Processor Units (TPU3)

- Three time processing units (TPU3)
  - 16 channels each
- Each TPU3 is a microcoded timer subsystem
- One 6-Kbyte and one 4-Kbyte dual-port TPU RAM (DPTRAM), one (6-Kbyte) shared by two TPU3 modules for TPU microcode and the 4-Kbyte dedicated to the third TPU3 for microcode.

### 1.2.11.2 22-Channel Modular I/O System (MIOS14)

- 22-channel MIOS timer (MIOS14)
- Six modulus counter submodules (MCSM)
  - Four additional MCSM submodules compared to MIOS1
- 10 double action submodules (DASM).
- 12 dedicated PWM submodules (PWMSM)
  - Four additional PWM submodules compared to MIOS1 (shared with MIOS GPIO pins)
- MIOS real-time clock submodule (MRTCSM) provides low power clock/counter
  - Requires external 32-KHz crystal
  - Uses four pins: two for 32-KHz crystal, two for power/ground.

### 1.2.12 Two Enhanced Queued Analog-to-Digital Converter Modules (QADC64E)

- Two enhanced queued analog to digital converters (QADC64E A, QADC64E B) with AMUXes for 40 total analog channels.
- 10 bit A/D converter with internal sample/hold
  - Typical conversion time is 4  $\mu$ s (250-Kbyte samples/sec)
  - Two conversion command queues of variable length
- Automated queue modes initiated by:
  - External edge trigger/level gate
  - Software command
  - Periodic/interval timer, assignable to both queue 1 and 2
- 64 result registers in each QADC64E module
  - Output data is right or left justified, signed or unsigned
- Synchronized clock mode allows both QADC64Es to see the same conversion clock. This allows the two modules to look like one large QADC with four queues.
- Conversions alternate reference (ALTREF) pin. This pin can be connected to a different reference voltage

### 1.2.13 Three CAN 2.0B Controller (TouCAN) Modules

- Three TouCAN modules (TouCAN\_A, TouCAN\_B, and TouCAN\_C)
- 16 message buffers each, programmable I/O modes
- Maskable interrupts
- Programmable loopback for self-test operation
- Independent of the transmission medium (external transceiver is assumed)
- Open network architecture, multimaster concept
- High immunity to EMI
- Short latency time for high-priority messages
- Low power sleep mode, with programmable wake up on bus activity
- TouCAN\_C pins shared with MIOS14 GPIO pins

## 1.2.14 Queued Serial Multi-Channel Modules (QSMCM)

- Two queued serial modules with one queued-SPI and two SCI each (QSMCM\_A, QSMCM\_B)
  - QSMCM\_A matches full MPC555 QSMCM functionality
  - QSMCM\_B has pins muxed with DLCMD2 module
    - Two pins are muxed with DLCMD2 (J1850) transmit and receive pins (B\_PCS3\_J1850\_TX and B\_RXD2\_J1850\_RX)
    - QSMCM B vs J1850 mux control provided by QPAPCS3 bit in QSMCM pin assignment register (PQSPAR)
- Queued-SPI
  - Provides full-duplex communication port for peripheral expansion or interprocessor communication
  - Up to 32 preprogrammed transfers, reducing overhead
  - Synchronous serial interface with baud rate of up to system clock / 4
  - Four programmable peripheral-select pins support up to 16 devices
  - Special wrap-around mode allows continuous sampling of a serial peripheral for efficient interfacing to serial analog-to-digital (A/D) converters
- SCI
  - UART mode provides NRZ format and half- or full-duplex interface
  - 16 register receive buffer and 16 register transmit buffer on one SCI
  - Advanced error detection, and optional parity generation and detection
  - Word length programmable as 8 or 9 bits
  - Separate transmitter and receiver enable bits, and double buffering of data
  - Wake-up functions allow the CPU to run uninterrupted until either a true idle line is detected, or a new address byte is received

## 1.2.15 Electrical Specifications and Packaging

- 40 MHz operation (56 MHz operation is optional for the MPC566)
- -40°C – 125°C ambient temperature, -40°C – 85°C for suffix C device, -55°C– 125°C for suffix A devices
- 2.6 V ± 0.1 V external bus
  - External bus is compatible with external memory devices operating from 2.5 V to 3.4 V.
  - Extended voltage range (2.7 – 3.4 V) degrades data drive timing by 1.1 ns on data writes.
- 2.6 ± 0.1 V internal logic
- 5-V I/O (5.0 ± 0.25 V)
- Available in package or bumped die
- Plastic ball grid array (PBGA) packaging
  - 388 ball PBGA
  - 27 mm x 27 mm body size
- 1.0 mm ball pitch

## 1.3 MPC565 Optional Features

The following features of the MPC565 are optional features and may not appear in certain configurations:

- 56-MHz operation (40-MHz is default)
- MPC566 supports code compression

## 2 Differences between the MPC565 and the MPC555

The MPC565 is an enhanced version of the MPC555. Most functional features of the MPC555 are unchanged on the MPC565. Table 2 shows the high level differences.

**Table 2. Differences Between Modules of the MPC555 and the MPC565**

Module	MPC555	MPC565
CPU Core	No Change	
BBC	BBC	BBC with improved code compression <sup>1</sup>
L2U	No Change	
SRAM	26-Kbytes	36-Kbyte CALRAM with overlay features
Flash	448-Kbyte CMF	1-Mbyte UC3F (new programming, etc.)
USIU	USIU	USIU with enhanced interrupt controller
JTAG	No Change	
READI	None	New Module
UIMB	No Change	
QADC64	2 QADC64 (16 channels on each QADC for 32 total channels)	2 QADC64E w/AMUXes (40 channels accessible from either QADC64E)
QSMCM	(1) No Change (2)	
DLCMD2 (J1850)	None	1
MIOS	MIOS1	MIOS14: MIOS1 with real-time clock (MRTCSM), 4 more PWMSMs and 4 more MCSMs
TouCAN	(2) No Change (3)	
TPU3	(2) No Change (3)	
DPTRAM	(6-Kbytes) No Change (6-Kbytes, 4-Kbytes)	
Power Supplies		
—	40 MHz with two power supplies: nominal 3.3-V to 5.0-V power supplies	56 MHz with two power supplies: 5.0-V I/O, 2.6-V internal logic

<sup>1</sup> Available on some options.

## 2.1 Additional MPC565 Differences

The following are additional differences between the MPC555 and the MPC565.

- SPI (MISO, MOSI, and SCK) pin drive.
  - MPC565 provides 21-ns rise/fall with 200-pf load using CMOS (20%/70%) levels
- GPIO on MODCK1 pin outputs only 2.6 V
  - MODCK1 pin is in keep-alive power section with no 5-V rail available
  - 5.0-V compatibility modes
    - Input is 5-V friendly
    - 2.6-V output has less slew rate control
    - 2.6-V:  $V_{OH} = 2.3\text{ V}$
- Power supplies for external bus pins
  - QVDDL is quiet supply to hold non-switching outputs quiet even when noisy supply (NVDDL) sags
  - QVDDL supplies pre-drive and other pad logic
  - NVDDL only supplies final PMOS driver stage
  - QVDDL and NVDDL shorted on customer board after filtering
- Pull-up and pull-down changes during PORESET and HRESET
  - All 2.6-V/5-V pads (external bus: address/data/control) pull down at reset
  - All 5-V pads pull up at reset
  - Additional control granularity in the PDMCR register
- No pull-ups on QSMCM SCI receive pads
- A\_RXD1\_QGPI1, A\_RXD2\_QGPI2, B\_RXD1\_QGPI1 pins do not have weak pull-up during reset or any other time
- CLKOUT has 3 drive strength options
  - Better matches drive to requirements to reduce EMI
  - 25, 50, 100 pf instead of 45 and 90 pf
- Change reset value of ENGCLK to maximum divide (crystal/128)
  - For a 4-MHz crystal, this is 31.25 KHz
    - ENGCLK is selectable between 2.6 V and 5 V
- A daisy chain between UC3F modules allows either module to provide the reset configuration word (RCW)
- Censorship operation
  - A RCW bit controls whether or not the entire UC3F can be erased while censorship is violated
- BBC SPRs (PPC regs) access in two clocks instead of one clock
- CALRAM internal protection block size is 8 Kbytes
  - Instead of 4 Kbytes on MPC555 LRAM
- CALRAM causes machine check exception instead of data storage interrupt (DSI) exception in certain cases
  - For non-overlay CPU core accesses, a DSI exception is taken
  - For overlay accesses and any non-core access (slave mode), a machine check exception is taken

- CALRAM causes DSI exception only if the data relocation (DR) bit in the core machine state register, MSR[DR], is set.
  - L2U on MPC555 already followed this protocol, but the LRAM did not. Now all L-bus peripherals follow this protocol.
  - The MSR[DR] bit is described in the reference manual for more information.
- Four additional PRDS control bits were added to the USIU to allow more granularity of PRDS control on a part
- BBC includes a 4-Kbyte DECRAM that can be used if compression is not used or is not available.

### 3 SRAM Keep-Alive Power Behavior

The SRAM has three keep-alive power pins (VDDSRAM1, VDDSRAM2, and VDDSRAM3). These pins provide keep-alive power to the SRAM arrays in the CALRAM modules and the DPTRAM modules.

The VDDSRAM1 pin powers the 32-Kbyte CALRAM A during keep-alive while power is off to the MPC565 (except for the keep-alive power supplies). CALRAM A keeps all of its 32 Kbytes powered during power down.

The VDDSRAM2 pin powers the 4-Kbyte CALRAM B module. The VDDSRAM3 pin powers the DPTRAM modules during keep-alive as well as during normal operation. The CALRAM modules only power their arrays from the VDDSRAM pins during keep-alive. During normal operation, they are powered by the normal internal VDD of the part.

The DPTRAM modules (6 Kbytes and 4 Kbytes) and the 4-Kbyte DECRAM in the BBC module power their arrays via the VDDSRAM3 pin during keep-alive and are supplied by VDD during normal operation.

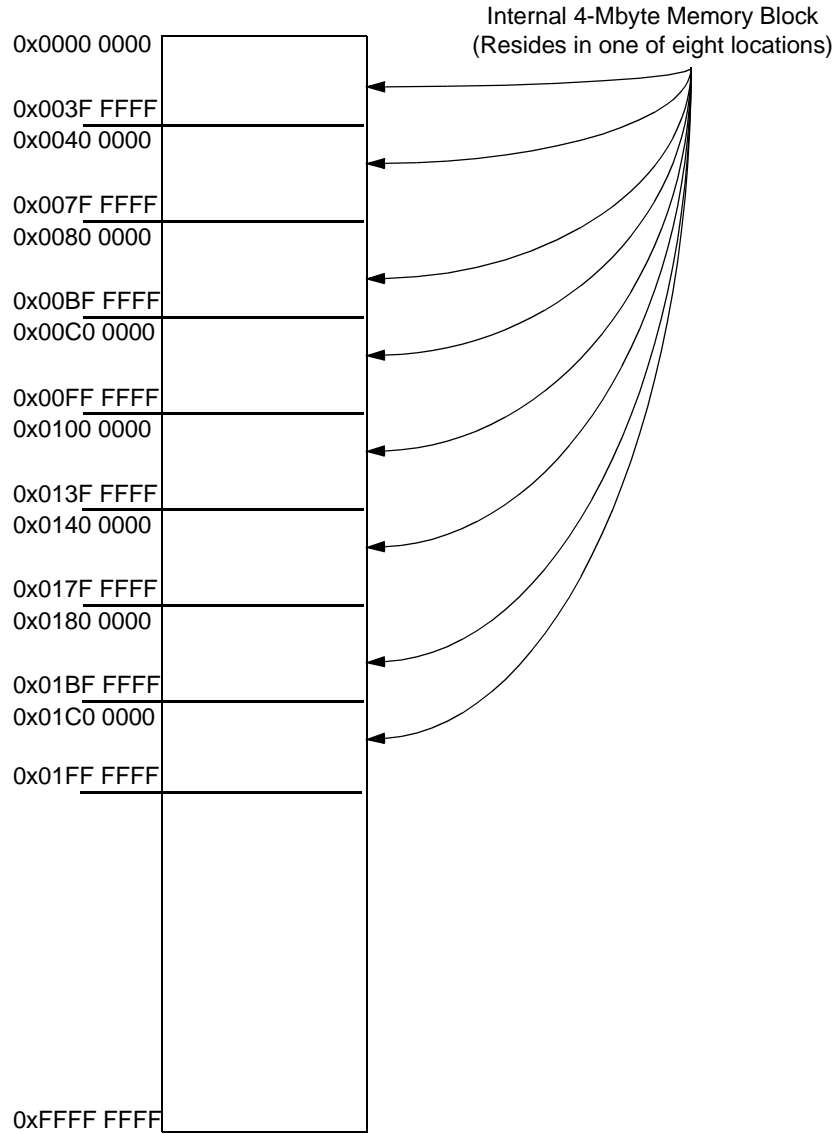
### 4 MPC565 Memory Map

The internal memory map is organized as a single 4-Mbyte block. This is shown in Figure 3. This block can be moved to one of eight different locations. The internal memory space is divided into the following sections:

- Flash memory (1 Mbyte) — U-bus memory
- Static RAM memory (36 Kbytes CALRAM) — L-bus memory
- Control registers and IMB3 modules (64 Kbytes), partitioned as
  - USIU and flash control registers
  - UIMB interface and IMB3 modules
  - CALRAM and READI control registers (L-bus control register space)

The internal memory block can reside in one of eight possible 4-Mbyte memory spaces. These eight locations are the first eight 4-Mbyte memory blocks starting with address 0x0000 0000, as shown in Figure 2. There is a user programmable register in the USIU to configure the internal memory map to one of the eight possible locations. Programmability of internal memory map location allows multiple chip system.

The IMB3 address space block in Figure 3 shows memory allocation for IMB3 modules. It does not show the actual memory space required for individual modules. All modules are mapped to the low address, numerically, of the memory allocated for that module in the IMB3 address space.



**Figure 2. Memory Map**

0x00 0000	UC3F_A Flash 512 Kbytes	USIU Control Registers	0x2F C000
0x07 FFFF		UC3F_A Control (64 bytes)	0x2F C800
0x08 0000	UC3F_B Flash 512 Kbytes	UC3F_B Control (64 bytes)	0x2F C840 0x2F C87F
0x0F FFFF			
0x10 0000	Reserved for Flash (2,016 Kbytes)		
0x2F 7FFF		DPTRAM_AB Registers (64 bytes)	0x30 0000
0x2F 8000	DECRAM 4 Kbytes	DPTRAM_C Registers (64 bytes)	0x30 0040
0x2F 8FFF		DLCMD2 (16 bytes)	0x30 0080
0x2F 9000	Reserved	Reserved (3952 bytes)	0x30 0090
0x2F 9FFF			
0x2F A000	BBC Control Registers 8 Kbytes	DPTRAM_C (4 Kbytes)	0x30 1000
0x2F BFFF		DPTRAM_AB (6 Kbytes)	0x30 2000
0x2F C000	USIU & Flash Control 16 Kbytes	Reserved (2 Kbytes)	0x30 3800
0x2F FFFF		TPU3_A (1 Kbytes)	0x30 4000
0x30 0000	UIMB I/F & IMB Modules 32 Kbytes	TPU3_B (1 Kbytes)	0x30 4400
0x30 7FFF		QADC64_A (1 Kbytes)	0x30 4800
0x30 8000	Reserved for IMB 480 Kbytes	QADC64_B (1 Kbytes)	0x30 4C00
0x37 FFFF		QSMCM_A (1 Kbytes)	0x30 5000
0x38 0000	CALRAM/ Readi Control 256 bytes	QSMCM_B (1 Kbytes)	0x30 5400
0x38 00FF		Reserved (1 Kbytes)	0x30 5800
0x38 0100	Reserved (L-bus Control) ~32 Kbytes	TPU3_C (1 Kbytes)	0x30 5C00
0x38 3FFF		MIOS14 (4 Kbytes)	0x30 6000
0x38 4000	Reserved (L-bus Mem) 444 Kbytes	TOUCAN_A (1 Kbytes)	0x30 7000
0x3F 6FFF		TOUCAN_B (1 Kbytes)	0x30 7400
0x3F 7000	All 4-Kbytes can be Overlay Section	TOUCAN_C (1 Kbytes)	0x30 7800
0x3F 7FFF	CALRAM_B (4 Kbyte)	Reserved (896 bytes)	0x30 7900
0x3F 8000		UIMB Control Registers (128 bytes)	0x30 7F80 0x30 7FFF
	CALRAM_A (32 Kbyte)		
	-----		
0x3F FFFF	4-Kbyte Overlay Section		

Figure 3. Internal Memory Block

# 5 MPC565 Pinout Diagram

Figure 4 shows the pinout for the MPC565.

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26
A	VDD ANA_B_PCB0	VBI ANA_AV_A_PCB1	VRE ALTRFE	AMB4 AMB5	AMB6 AMB7	AMB8 ANA_AV_A_PCB2	AMB9 ANA_AV_A_PCB3	AMB10 ANA_AV_A_PCB4	AMB11 ANA_AV_A_PCB5	AMB12 ANA_AV_A_PCB6	AMB13 ANA_AV_A_PCB7	AMB14 ANA_AV_A_PCB8	AMB15 ANA_AV_A_PCB9	AMB16 ANA_AV_A_PCB10	AMB17 ANA_AV_A_PCB11	AMB18 ANA_AV_A_PCB12	AMB19 ANA_AV_A_PCB13	AMB20 ANA_AV_A_PCB14	AMB21 ANA_AV_A_PCB15	AMB22 ANA_AV_A_PCB16	AMB23 ANA_AV_A_PCB17	AMB24 ANA_AV_A_PCB18	AMB25 ANA_AV_A_PCB19	AMB26 ANA_AV_A_PCB20	AMB27 ANA_AV_A_PCB21
B	VSS	VDD	VDD	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS
C	VDDRTC	VSS	VDD	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS
D	EXTAL32	VDD32K	VSS	VDD	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS
E	XITAL32	B_CMTX6	VDD32K	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS
F	VSSRTC	C_TRU008	C_TRU009	MD01	MD02	MD03	MD04	MD05	MD06	MD07	MD08	MD09	MD10	MD11	MD12	MD13	MD14	MD15	MD16	MD17	MD18	MD19	MD20	MD21	
G	C_TRU010	C_TRU011	C_TRU012	VDD32K	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS
H	C_TRU013	C_TRU014	C_TRU015	C_TRU016	C_TRU017	C_TRU018	C_TRU019	C_TRU020	C_TRU021	C_TRU022	C_TRU023	C_TRU024	C_TRU025	C_TRU026	C_TRU027	C_TRU028	C_TRU029	C_TRU030	C_TRU031	C_TRU032	C_TRU033	C_TRU034	C_TRU035	C_TRU036	
J	C_TRU037	C_TRU038	C_TRU039	C_TRU040	C_TRU041	C_TRU042	C_TRU043	C_TRU044	C_TRU045	C_TRU046	C_TRU047	C_TRU048	C_TRU049	C_TRU050	C_TRU051	C_TRU052	C_TRU053	C_TRU054	C_TRU055	C_TRU056	C_TRU057	C_TRU058	C_TRU059	C_TRU060	
K	C_TRU061	C_TRU062	C_TRU063	C_TRU064	C_TRU065	C_TRU066	C_TRU067	C_TRU068	C_TRU069	C_TRU070	C_TRU071	C_TRU072	C_TRU073	C_TRU074	C_TRU075	C_TRU076	C_TRU077	C_TRU078	C_TRU079	C_TRU080	C_TRU081	C_TRU082	C_TRU083	C_TRU084	
L	MDL0	TDC_DSEK	MDL1	MCKI	MCKO	MDL0	MDL1	MDL2	MDL3	MDL4	MDL5	MDL6	MDL7	MDL8	MDL9	MDL10	MDL11	MDL12	MDL13	MDL14	MDL15	MDL16	MDL17	MDL18	
M	TDLSE0	EVTL_B	RSTL_B	MSELB	MSEL0	MSEL1	MSEL2	MSEL3	MSEL4	MSEL5	MSEL6	MSEL7	MSEL8	MSEL9	MSEL10	MSEL11	MSEL12	MSEL13	MSEL14	MSEL15	MSEL16	MSEL17	MSEL18	MSEL19	
N	TRIS	MDL0	MDL1	MDL2	MDL3	MDL4	MDL5	MDL6	MDL7	MDL8	MDL9	MDL10	MDL11	MDL12	MDL13	MDL14	MDL15	MDL16	MDL17	MDL18	MDL19	MDL20	MDL21	MDL22	
P	MDL23	JCOMP	MCKO	MDL0	MDL1	MDL2	MDL3	MDL4	MDL5	MDL6	MDL7	MDL8	MDL9	MDL10	MDL11	MDL12	MDL13	MDL14	MDL15	MDL16	MDL17	MDL18	MDL19	MDL20	
R	MDL21	TRD_DISE0	MDL2	MDL3	MDL4	MDL5	MDL6	MDL7	MDL8	MDL9	MDL10	MDL11	MDL12	MDL13	MDL14	MDL15	MDL16	MDL17	MDL18	MDL19	MDL20	MDL21	MDL22	MDL23	
T	MDL24	MISO_B	MPU_FRZ_PFLC	SFP02_A	SFP02_B	SFP02_C	SFP02_D	SFP02_E	SFP02_F	SFP02_G	SFP02_H	SFP02_I	SFP02_J	SFP02_K	SFP02_L	SFP02_M	SFP02_N	SFP02_O	SFP02_P	SFP02_Q	SFP02_R	SFP02_S	SFP02_T	SFP02_U	
U	SFP02_V	SFP02_W	SFP02_X	SFP02_Y	SFP02_Z	SFP02_AA	SFP02_AB	SFP02_AC	SFP02_AD	SFP02_AE	SFP02_AF	SFP02_AG	SFP02_AH	SFP02_AI	SFP02_AJ	SFP02_AK	SFP02_AL	SFP02_AM	SFP02_AN	SFP02_AO	SFP02_AP	SFP02_AQ	SFP02_AR	SFP02_AS	
V	SFP02_AT	SFP02_AU	SFP02_AV	SFP02_AW	SFP02_AX	SFP02_AY	SFP02_AZ	SFP02_B0	SFP02_B1	SFP02_B2	SFP02_B3	SFP02_B4	SFP02_B5	SFP02_B6	SFP02_B7	SFP02_B8	SFP02_B9	SFP02_BA	SFP02_BB	SFP02_BC	SFP02_BD	SFP02_BE	SFP02_BF	SFP02_BG	
W	SFP02_BH	SFP02_BI	SFP02_BJ	SFP02_BK	SFP02_BL	SFP02_BM	SFP02_BN	SFP02_BO	SFP02_BP	SFP02_BQ	SFP02_BR	SFP02_BS	SFP02_BT	SFP02_BU	SFP02_BV	SFP02_BW	SFP02_BX	SFP02_BY	SFP02_BZ	SFP02_C0	SFP02_C1	SFP02_C2	SFP02_C3	SFP02_C4	
Y	SFP02_C5	SFP02_C6	SFP02_C7	SFP02_C8	SFP02_C9	SFP02_CA	SFP02_CB	SFP02_CC	SFP02_CD	SFP02_CE	SFP02_CF	SFP02_CG	SFP02_CH	SFP02_CI	SFP02_CJ	SFP02_CK	SFP02_CL	SFP02_CM	SFP02_CN	SFP02_CO	SFP02_CP	SFP02_CQ	SFP02_CR	SFP02_CS	
AA	SFP02_CT	SFP02_CU	SFP02_CV	SFP02_CW	SFP02_CX	SFP02_CY	SFP02_CZ	SFP02_D0	SFP02_D1	SFP02_D2	SFP02_D3	SFP02_D4	SFP02_D5	SFP02_D6	SFP02_D7	SFP02_D8	SFP02_D9	SFP02_DA	SFP02_DB	SFP02_DC	SFP02_DD	SFP02_DE	SFP02_DF	SFP02_DG	
AB	SFP02_DH	SFP02_DI	SFP02_DJ	SFP02_DK	SFP02_DL	SFP02_DM	SFP02_DN	SFP02_DO	SFP02_DP	SFP02_DQ	SFP02_DR	SFP02_DS	SFP02_DT	SFP02_DU	SFP02_DV	SFP02_DW	SFP02_DX	SFP02_DY	SFP02_DZ	SFP02_E0	SFP02_E1	SFP02_E2	SFP02_E3	SFP02_E4	
AC	SFP02_E5	SFP02_E6	SFP02_E7	SFP02_E8	SFP02_E9	SFP02_EA	SFP02_EB	SFP02_EC	SFP02_ED	SFP02_EE	SFP02_EF	SFP02_EG	SFP02_EH	SFP02_EI	SFP02_EJ	SFP02_EK	SFP02_EL	SFP02_EM	SFP02_EN	SFP02_EO	SFP02_EP	SFP02_EQ	SFP02_ER	SFP02_ES	
AD	SFP02_ET	SFP02_EU	SFP02_EV	SFP02_EW	SFP02_EX	SFP02_EY	SFP02_EZ	SFP02_F0	SFP02_F1	SFP02_F2	SFP02_F3	SFP02_F4	SFP02_F5	SFP02_F6	SFP02_F7	SFP02_F8	SFP02_F9	SFP02_FA	SFP02_FB	SFP02_FC	SFP02_FD	SFP02_FE	SFP02_FF	SFP02_FG	
AE	SFP02_FH	SFP02_FI	SFP02_FJ	SFP02_FK	SFP02_FL	SFP02_FM	SFP02_FN	SFP02_FO	SFP02_FP	SFP02_FQ	SFP02_FR	SFP02_FS	SFP02_FT	SFP02_FU	SFP02_FV	SFP02_FW	SFP02_FX	SFP02_FY	SFP02_FZ	SFP02_G0	SFP02_G1	SFP02_G2	SFP02_G3	SFP02_G4	
AF	SFP02_G5	SFP02_G6	SFP02_G7	SFP02_G8	SFP02_G9	SFP02_GA	SFP02_GB	SFP02_GC	SFP02_GD	SFP02_GE	SFP02_GF	SFP02_GG	SFP02_GH	SFP02_GI	SFP02_GJ	SFP02_GK	SFP02_GL	SFP02_GM	SFP02_GN	SFP02_GO	SFP02_GP	SFP02_GQ	SFP02_GR	SFP02_GS	

NOTE: This is a top down view of the balls.

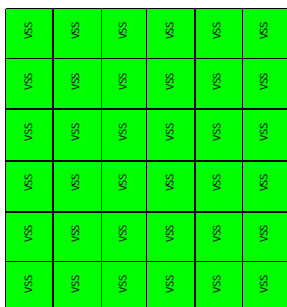


Figure 4. MPC565 Pinout Diagram



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